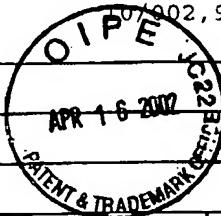


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FORM PTO-1449								Atty. Docket Number: H60-104 US	Serial Number: 07002,996
LIST OF PRIOR ART CITED BY APPLICANT								Applicant: J. Ramm	Group: 1
								Filing Date: 10/25/01	



## U.S. PATENT DOCUMENTS

EI*		Document Number							Date	Name		Class	Sub-class	Filing Date
FH	AA	4	0	5	8	4	3	0	11/15/77	Suntola et al.		156	611	11/25/75
↑	AB	4	3	8	9	9	7	3	06/28/83	Suntola et al.		118	275	12/11/81
	AC	4	4	1	3	0	2	2	11/01/83	Suntola et al.		427	255.2	06/21/79
	AD	5	0	7	1	6	7	0	12/10/91	Kelly		427	38	06/11/90
	AE	5	9	1	6	3	6	5	06/29/99	Sherman		117	92	08/16/96
↓	AF	5	9	7	2	4	3	0	10/26/99	DiMeo, Jr. et al.		427	255.3	11/26/97
FH	AG	6	0	1	5	5	9	0	01/18/00	Suntola et al.		427	255.2	11/28/95
	AH													
	AI													
	AJ													
	AK													

## FOREIGN PATENT DOCUMENTS

		Document Number							Date	Country		Class	Sub-class	Translated		
															Y	N
	AL															
	AM															
	AN															
	AO															
	AP															

## Other Prior Art (incl. Author, Title, Date, Pertinent Pages, etc.)

FH	AR	Hiramatsu, K, et al!, "Formation of Tin films with low Cl concentration by pulsed plasma chemical vapor deposition", <u>J. Vac. Sci. Technol. A</u> 14(3) May/Jun 1996, 1037-1040.
FH	AS	Rossnagel, S.M., "Plasma-enhanced atomic layer deposition of Ta and Ti for interconnect diffusion barriers", <u>J. Vac. Sci. Technol. B</u> 18(4), Jul/Aug 2000, 2016-2020.
FH	AT	Swiss Search Report, dated July 27, 2001.

Examiner: J. Ramm Date Considered: 7/14/04

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with N  
Draw line through citation if not in conformance and not considered. Include copy of this  
next communication to applicant.